



International Workshop on

Advanced Patterning Solutions

The 10th International Workshop on Advanced Patterning Solutions

第十届国际先进光刻技术研讨会

September 10-11, 2026, Shenzhen World, Shenzhen, Guangdong Province, China

2026 年 09 月 10 日至 11 日，深圳国际会展中心，广东深圳，中国

(September 09 for registration, 9 月 9 日注册)

Agenda 会议日程

Program Chairs:

Jiangliu Shi 师江柳, Chief Scientist, SAMT

Shisheng Xiong 熊诗圣, Professor, Zhangjiang Lab

Zongchang Yu 俞宗强, President, DJEL

Registration 注册		
09 Sep. 2026	14:00-17:00	Front of Mangrove A, Second Floor, South Lobby, Shenzhen World 深圳国际会展中心南登录大厅，2 层，红树林厅 A 前
10-11 Sep. 2026	08:00-17:00	
<u>DAY 1:</u>		
<u>10 Sep. 2026 (Thursday)</u>		
Mangrove A, Second Floor, South Lobby, Shenzhen World 深圳国际会展中心－南登录大厅，2 层，红树林厅 A		
<u>DAY 1-Morning</u>		
08:30-09:00	Opening Ceremony & Welcome Address Chair: Yayi Wei	
Welcome Address	Conference Chairs Address Host/Organizer Address	
09:00-10:10	Plenary Session I Chair: Shisheng Xiong (Zhangjiang Lab)	
	<i>5 minutes Q&A for each talk</i>	
09:00-09:35	Han Wang (The University of Hong Kong): (KEYNOTE) A Novel Nanomaterials Composite Pellicle for Advanced Lithography	
09:35-10:10	Ye Lu (Fudan University): (KEYNOTE) How AI is going to help accelerate DTCO?	
10:10-10:40	Group Photo & Coffee Break	
10:40-11:50	Plenary Session II Chair: Zongchang Yu (DJEL)	
	<i>5 minutes Q&A for each talk</i>	

10:40-11:15	Nan Lin (Beihang University): (KEYNOTE) Next Generation of Laser Driven EUV source
11:15-11:50	Kris Leask (Mycronic AB): (KEYNOTE) A cost-effective registration metrology solution for binary and phase-shift photomasks
11:50-13:50	Poster Session Authors should be present at your poster.
12:00-13:00	Lunch
DAY 1-Afternoon	
13:50-15:40	Patterning Session Chairs: Jiangliu Shi (SAMT) & Yaobin Feng (YMTC)
	<i>5 minutes Q&A for each talk</i>
13:50-14:25	Qiang Wu (Fudan University): (KEYNOTE) Physical Mask, Photoresist, Lithography Model, and DICO
14:25-14:50	Wenzhang Li (Fujian Jinhua Integrated Circuit Co., Ltd): (INVITED) Etch Model application in SADP and Cut Processes: Contour simulation and PWQ Prediction
14:50-15:15	Yoshiaki Yamada (Cobetter): (INVITED) Metal Removal Filter Membranes with Acid Resistance for Lithography Chemical Applications
15:15-15:40	Si Wu (University of Science and Technology of China): (INVITED) Reversible photoresists for nanoimprint lithography
15:40-16:10	Coffee Break
16:10-17:25	AI + Lithography Session Chairs: Weimin Gao (Tsinghua Univ.) & Junwei Lu (CXMT)
	<i>5 minutes Q&A for each talk</i>
16:10-16:35	Yuzhe Ma (The Hong Kong University of Science and Technology (Guangzhou)): (INVITED) Robust, Manufacturable, and Curvilinear Optical Proximity Correction
16:35-17:00	Hao Geng (ShanghaiTech University): (INVITED) Paradigm Shift in AI-Driven Semiconductor Manufacturing: Point Tool, Foundation Model, and Agent
17:00-17:25	Le Hong (Siemens): (INVITED) Advanced ML/AI design-technology co-optimization (DTCO) accelerates process node development ramp-up
18:30-18:35	Best Poster Award 最佳墙报颁奖 Mangrove C, Second Floor, South Lobby, Shenzhen World 深圳国际会展中心—南登录大厅, 2层, 红树林厅 C

18:35-20:00	Welcome Banquet for all attendees 晚宴 Mangrove C, Second Floor, South Lobby, Shenzhen World 深圳国际会展中心—南登录大厅，2层，红树林厅 C
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Day 2: 11 Sep. 2026 (Friday) – – Parallel Session I, 并行报告会场 I Hall 5, 2nd Floor, South Lobby, Shenzhen World 深圳国际会展中心—南登录大厅，2层5号会议室	
DAY 2-Morning	
08:30-10:05	Equipment Session Chairs: Kaidong Xu (Leuven Instruments) & Yun Zhan (XMC)
	<i>5 minutes Q&A for each talk</i>
08:30-08:55	Taiyen Peng (Leuven Instruments): (INVITED) Optimizing photoresist line-width roughness via combined ICP and ion beam shaping process
08:55-09:20	Tianyuan Chen (SMEE): (INVITED) Research on Simulation Strategies for Decomposing CDU Error Terms in KrF Lithography Systems
09:20-09:45	Fang-fang Duan (ASML): (INVITED) High accuracy, high throughput large field XT260 designed for supporting 3DIC and silicon interposer roadmaps
09:45-10:05	Likun Dong (Lithography Equipment Manufacturing Technology Innovation Center): Research on Thermal Time-Constant Model and influencing Factors of Cooling Water for Motor Used in Semiconductor-Equipment
10:05-10:30	Coffee Break
10:30-12:05	Metrology and Inspection Session I Chairs: Nan Lin (Beihang University) & Liguozhang (SEIDA)
	<i>5 minutes Q&A for each talk</i>
10:30-10:55	Chih-Hung Hsieh (Siemens): (INVITED) Advancing Massive Metrology for Next-Generation Semiconductor Manufacturing
10:55-11:20	Oracle Shen (Carl Zeiss): (INVITED) Extended Portfolio and New Features for More Flexibility in Registration Measurement
11:20-11:45	Puja Kadkhoda (OPTEST GmbH): (INVITED) Precision measurement techniques for quality control of VUV optical components
11:45-12:05	Lijun Zhou (Zhejiang University): Wafer alignment using vortex-beam interferometry
12:05-13:30	Lunch
DAY 2-Afternoon	

13:30-14:55	Metrology and Inspection Session II Chairs: Dean Wu (YMTTC) & Jin Li (KLA)
	<i>5 minutes Q&A for each talk</i>
13:30-13:55	Maohua Ren (United Semiconductor (Xiamen) Co., Ltd.): (INVITED) Preliminary study of focus-dependent process window assessment using Reticle Inspection Images
13:55-14:15	Huajun Zhang (Lithography Equipment Manufacturing Technology Innovation Center): Co-simulation technology of multi-axis heterodyne interferometer
14:15-14:35	Cheng Li (Hangzhou Institute for Advanced Study, UCAS): Transparent-Material-Compatible Hierarchical Alignment for Nanoimprint Lithography Using Diffraction-Enhanced Markers and Moiré Amplification
14:35-14:55	Yuhang He (Tsinghua University): LASSO-based Zernike-Legendre overlay decomposition
14:55-15:20	Coffee Break
15:20-16:45	Other Lithography Technology Session Chairs: Cuifang Kuang (Zhejiang University) & Jicheng Feng (ShanghaiTech University)
	<i>5 minutes Q&A for each talk</i>
15:20-15:45	Jicheng Feng (ShanghaiTech University): (INVITED) Atomic-level arrangement of matter into structural arrays
15:45-16:05	Ruobing Bai (Shanghai Jiao Tong University): DNA-directed assembly to complement EUV for sub-5 nm patterning
16:05-16:25	Haoyu Kan (Hangzhou Institute for Advanced Study, UCAS): Voltage-dependent pattern evolution and process window establishment in localized interface-heating ultrafast thermal nanoimprint lithography
16:25-16:45	Na Li (Shanghai University): Desk-scale EUV exposure system based on Xe-DPP source and talbot lithography for sub-100 nm photoresist patterning
16:45-16:50	Closing Plenary Address 闭幕致辞 Chairs: Shisheng Xiong (Zhangjiang Lab)

Day 2:	
11 Sep. 2026 (Friday) – – Parallel Session II, 并行报告会场 II	
Hall 6, 2nd Floor, South Lobby, Shenzhen World	
深圳国际会展中心—南登录大厅, 2层6号会议室	
DAY 2-Morning	
08:30-10:25	AI + Computational Lithography Session Chairs: Xu Ma (BIT) & Kan Zhou (Haina Institute of Engineering)
	<i>5 minutes Q&A for each talk</i>
08:30-08:55	Zizheng Cao (Zhejiang University):

	(INVITED) AI-Accelerated Computational Lithography: Toward Lightweight and Interpretable Mask Synthesis for Advanced Nodes
08:55-09:20	Shengrui Zhang (DJEL): (INVITED) AI-powered hotspot prediction for patterning from SEM contour: physics-hybrid and pure AI models
09:20-09:45	Shanqi Tao (AMEDAC): (INVITED) Automated lithography modeling workflow based on general-purpose agent architecture: from dedicated physical models to scalable AI agents
09:45-10:05	You Wu (Tsinghua University): Photoresist contour-supervised deep learning for ILT
10:05-10:25	Yu Feng (Fudan University): GNN-Guided Local Refinement for Efficient Layout Decomposition with DSA-MP
10:25-10:45	Coffee Break
10:45-12:10	AI + DTCO Session Chairs: Chen Shen (PFTN) & Xiaoming Liu (Empyrean Tech)
	<i>5 minutes Q&A for each talk</i>
10:45-11:10	Ningmu Zou (Nanjing University): (INVITED) DVCC-GNN: A dual-view cross-channel graph neural network for lithography hotspot detection
11:10-11:30	Caiwei Shang (Fudan University): AI-driven closed-loop simulation framework for DSA toward DTCO in logic chip manufacturing
11:30-11:50	Yuyang Liu (Nanjing University): CHROME: Contact hole robust optimization via multi-objective evolution
11:50-12:10	Fengyun Long (Guangdong University of Technology): DPFF-driven parametric curvilinear mask rule compliance
12:10-13:30	Lunch
DAY 2-Afternoon	
13:30-14:55	Computational Lithography Session Chairs: Jing Li (Zhejiang Univeristy) & Feng Shao (Siemens)
	<i>5 minutes Q&A for each talk</i>
13:30-13:55	Jie Liu (ASML-Cymer): (INVITED) Convolved Bandwidth (CBW): A New Laser Bandwidth Metric for Improved CD Matching and EPE Reduction
13:55-14:15	Minhao Wu (NICIC): A hyper-NA EUV SMO and hot spot removal study with 16 nm minimum pitch and low n and high k absorbers
14:15-14:35	Hanzhi Zhang (Changchun University of Science and Technology): The High-Efficiency EUV Mask Optimization Method Based on

	Pixelated Absorber Layer Correction
14:35-14:55	Rui Lian (Beijing Institute of Technology): Seed-guided parallel phase unwrapping with bucket sorting and overlapped sub-blocks
14:55-15:20	Coffee Break
15:20-17:05	Computational Lithography and Process Session Chairs: Sikun Li (SIOM) & Yijiang Shen (Guangdong University of Technology)
	<i>5 minutes Q&A for each talk</i>
15:20-15:45	Kobelkov Sergey (Huawei Technologies Ltd. & Lomonosov Moscow State University): (INVITED) Shot-Count Aware Inverse Lithography Technology via Geometric Regularization
15:45-16:05	Jinghong Liu (Beijing Superstring Academy of Memory Technology): Surface restoration mechanisms in 3D structure staircase fabrication: mitigating photoresist scumming and delamination on fluorinated poly-silicon trenches
16:05-16:25	Ignat Moskalenko (Huawei Technologies Ltd.): New approach for OPC model self-consistency improvement
16:25-16:45	Haofeng Guo (Changchun Institute of Optics, Fine Mechanics and Physics, CAS): A Boundary-Iterative Hybrid Method Combining Runge-Kutta BPM and Multilayer Transfer Matrices for Mask Imaging
16:45-17:05	Yuxiang Yin (ShanghaiTech University): Electric Proximity Correction for Faraday Lithography
17:05-17:10	Closing Plenary Address 闭幕致辞 Chairs: Zongchang Yu (DJEL)

Day 2:	
11 Sep. 2026 (Friday) – – Parallel Session III, 并行报告会场 III	
Hall 9, 2nd Floor, South Lobby, Shenzhen World	
深圳国际会展中心—南登录大厅，2层9号会议室	
DAY 2-Morning	
08:30-10:10	Photoresist Session Chairs: Guoqiang Yang (ICCAS) & Xudong Guo (ICCAS)
	<i>5 minutes Q&A for each talk</i>
08:30-08:55	Ming-Qiang Zhu (Huazhong University of Science and Technology): (INVITED) Multi-tone photopatterning via photoacid-induced crosslinking/degradation of poly(2,3-dihydrofuran)
08:55-09:20	Hideaki Tsubaki (Fujifilm Corporation): (INVITED) Reconsidering the role of fluorinated materials in

	advanced ArF immersion resists: Toward fluorine-free material design
09:20-09:45	Huie Zhu (Zhangjiang Lab): (INVITED) AI-Driven pKa Prediction of Photoacid Generators
09:45-10:10	Victor Sumerin (Pibond): (INVITED) High-temperature, gap filling, planarizing SOC materials for advanced ArF and EUV processes
10:10-10:40	Coffee Break
10:40-12:15	X-Ray for Lithography Session Chairs: Xiaosong Liu (USTC) & Guangcai Chang (IHEPCAS)
	<i>5 minutes Q&A for each talk</i>
10:40-11:05	Zhao Wu (National Synchrotron Radiation Laboratory, University of Science and Technology of China,): (INVITED) Recent researches on extreme ultraviolet lithography at the Hefei light source
11:05-11:30	Zirui Gao (Institute of High Energy Physics, CAS): (INVITED) Nano-resolution nondestructive 3D imaging capabilities of microchips at the HEPS ID19 beamline
11:30-11:55	Peng Li (National Synchrotron Radiation Laboratory, University of Science and Technology of China): (INVITED) A coherent lensless microscope for EUV mask inspection at Hefei Light Source
11:55-12:15	Yike Chen (Shanghai Synchrotron Radiation Facility and East China University of Science and Technology): Laser-assisted post-exposure baking for maskless grayscale lithography based on photoacid diffusion control
12:15-13:30	Lunch
DAY 2-Afternoon	
13:30-15:10	Mask Session I Chairs: Modern Xu (Carl Zeiss) & David H. Wei (GDUT)
	<i>5 minutes Q&A for each talk</i>
13:30-13:55	Sebastian Vollmar (Carl Zeiss SMT GmbH): (INVITED) Overcoming throughput and capability limits in photomask repair: a roadmap perspective
13:55-14:20	Hongyan Yang (SUSS MicroTec (Shanghai) Co., Ltd): (INVITED) Develop Process: Hardware Solutions
14:20-14:45	Jie Liu (Hunan University): (INVITED) A Scalable Model-Based Curvilinear Mask Fracturing Method with Overlapping Shots
14:45-15:10	Jingwei Chen (Mycronic (Shanghai) Co., Ltd.): (INVITED) Extending mature node mask manufacturing beyond EOL tools

15:10-15:30	Coffee Break
15:30-17:00	Mask Session II
	Chair: Lifeng Duan (Yuweitek) & Jie Liu (Hunan University)
	<i>5 minutes Q&A for each talk</i>
15:30-15:55	Zhengzhou Tian (New Ray Mask Technology Corporation): (INVITED) Production Qualification of a New Optical Photomask Inspection Platform for Mature-Node Reticle Quality Control
15:55-16:20	Xijun Li (Zhejiang Fuxi Opto-electronic Manufacturing Co., Ltd.): (INVITED) Hybrid photomask and wafer direct imaging using a DUV mask writer
16:20-16:40	Li Liu (Huazhong University of Science and Technology): Pushing the Resolution Limit of Coherent Diffractive Imaging
16:40-17:00	Yatian Zhang (Beijing Institute of Technology): Adaptive grid expansion for single-shear fourier wavefront reconstruction in lateral shearing interferometry
17:00-17:05	Closing Plenary Address 闭幕致辞 Chairs: Jiangliu Shi (SAMT)

Agenda is subject to change

Poster Session**10 Sep. 2026****11:50-13:50 Outdoor of Mangrove A 红树林厅前廊**

Poster-007	Junqi Yang* , Rui Xu, Jiaqi Liu, Chenxing Dong, Chuan Zhang (Zhangjiang Laboratory) Efficient inverse lithography technology based on a self-supervised swinIR model
Poster-011	Shiyang Li, Linzi Wu, Bojian Wu, Hengbo Li, Xiaolei Wen, Keqiang Qiu* , Zhao Wu, Yilin Hong (National Synchrotron Radiation Laboratory, University of Science and Technology of China) Achromatic Talbot lithography with Au transmission gratings achieves 20 nm half-pitch resolution
Poster-017	Wei Zhu^{1,*}, Sheng Huang¹, Allen Wu¹, Bin Zou², Haotian Zhu², Liying Jiang² (¹ Nexchip Semiconductor Corporation; ² Shanghai Yuwei Semiconductor Technology Corporation) A systematic investigation of mark design in advanced lithography
Poster-030	Ankita Agarwal¹, Rachit Sharma¹, Ingo Bork², Vineeth Muralidharan¹, Manachala Snehith Reddy¹, Ranganadh Peesapati¹ (¹ Siemens Digital Industries Software, Nalapad Brigade Centre; ² Siemens Digital Industries Software, Santa Clara) EPE aware shot placement for fracture of AR/VR photomasks
Poster-031	Zilang Wu¹, Yizhen Song², Weixuan Zeng², Xin Zhang^{2,*}, Shisheng Xiong^{1,2,*} (¹ Fudan University; ² Zhangjiang Laboratory) Explaining and resolving thickness dependence of microdomain orientation by extensive simulation of directed self-assembly
Poster-033	Wang Kang[*], Lv Pan, Luo Zhaolong (Nexchip Semiconductor Corporation) ML-Driven Topography Bias Compensation in OPC for Enhanced Implant patterning
Poster-036	Amogh Raj¹, Rachit Sharma¹, Ranganadh Peesapati¹, Ingo Bork², Stephen Kim² (¹ Siemens Digital Industries Software, Nalapad Brigade Centre; ² Siemens Digital Industries Software, Santa Clara) Printability-Aware MDP Verification for Curvilinear Masks Written with VSB Mask Writers
Poster-037	Caiwei Shang^{1,2}, Chenran Zhang^{1,2}, Donghao Han^{1,2}, Rujie Cao³, Yan Zhang², Zili Li¹, Weixuan Zeng^{2,*}, Shisheng Xiong^{1,2,*} (¹ Fudan University; ² Zhangjiang laboratory; ³ Shanghai Jiao Tong University) Simulation of overfilled Directed self-assembly contact holes for process window mapping from hole shrinkage to multiplication with compact model
Poster-038	Lin Sijun^{1,2}, Wu Zhipeng^{1,2,*}, Qi Yuejing^{1,2,*}, Zhu Liling^{1,2}, Lu Shiqing^{1,2}, Zhou Xin¹ (¹ Institute of Microelectronics of the Chinese Academy of Sciences; ² University of Chinese Academy of Sciences) Multi-scale Attention Enhanced ViT with Manual-feature-guided Gated Fusion for Wafer Defect Classification
Poster-041	Yin shiqi[*], Wang kang, Luo zhaolong (Nexchip Semiconductor Corporation)

	Density-dependent sizing and MRC-free OPC solution for advanced-node lithography enhancement
Poster-042	Zhihao Zhao* , Haifeng Li [#] , Rui Ding, Weiqiang Xu, Yu Huang, Jianliang Lin, Jianhong Wu, Weichung Ma, Zhaolong Luo (<i>Nexchip Semiconductor Corporation</i>) Mechanism and Optimization of Electrostatic Adsorption-Induced Residue Defects in High-Density Photoresist Regions of Contact/Via Layers After Development
Poster-044	Hao Cheng^{1,*} , Wang Kang ¹ , Luo Zhaolong ¹ , Zhang Yihan ² , Hu Caoping ² (<i>¹Nexchip Semiconductor Corporation; ²Advanced Manufacturing EDA Co., Ltd</i>) Resource Allocation Optimization, Acceleration Characteristics, and Reliability Study of GPU-Accelerated Optical Proximity Correction
Poster-050	Yong Shi ^{1,*} , Caleb Wang ¹ , Chunhung Wu ¹ , Wenchun Huang (<i>AMEGADAC</i>) Reducing AF Missing in RBAF via Sub-Conflict Seed Retention
Poster-058	Cai Chen ¹ , Xiaodone Meng ^{1,2,*} , Hongbin Zhang ¹ , Jinhua Pei ¹ , Minchun Yang ¹ , Qi Zhang ¹ , Yebin Xu ¹ , Richard Zheng ¹ (<i>¹Advanced Manufacturing EDA Co., Ltd.; ²School of Integrated Circuits, Tsinghua University</i>) Improving OPC Simulation Accuracy via a Differentiable Additive Correction Framework
Poster-059	Jieyun Chen, Liang Xu* , Wenzhuang Liu, Yebin Xu, Qiang Yin, Haoming Guo, Richard Zheng (<i>AMEDAC</i>) High Sensitivity Contact Defect Detection based on Intra-FOV Average Contour
Poster-063	Fang Yin* , Zichen Yin, Pei Xie, Can Duan, Jazlyn Zhang (<i>STIC</i>) Optical mechanism analysis of photoresist peeling hotspots and detection in Optical Proximity Correction (OPC) verify
Poster-065	Shiyang Gao ¹ , Ningyuan Yang ² , Quanji Zhang ¹ , Shaowei Jin ¹ , Riqiang Huang ¹ , Xin Zhuang ^{1,*} , Xing Cheng ^{1,*} (<i>¹Department of Materials Science and Engineering, Southern University of Science and Technology; ²Department of Chemistry, Southern University of Science and Technology</i>) A New Type of Silicon-containing Epoxy Photoresist
Poster-066	Guowei Jiang, Di Liang, Ziqiang Liang, Xin Wei, Yaokun Li, Kaicong Liu (<i>Beijing Superstring Academy of Memory Technology</i>) Study of Multilayer Reticule Overlay Compensation
Poster-069	Jinjie Qu, Liang Xu* , Weizhu Ni, Qixin Xu, Haoming Guo, Jieyun Chen, Yi Lu (<i>AMEDAC SEBU DTCO</i>) High-efficiency AI SEM contour extraction for hotspot detection
Poster-073	Yihao Wu ¹ , Xinliang Li ² , Shisheng Xiong ^{1,2,*} (<i>¹Fudan University; ²Zhangjiang laboratory</i>) Accelerating defect inspection of Directed Self-Assembly with defect-aware image translation
Poster-074	Kaisheng Chen (<i>SemiMask Corp.</i>) Modeling the optical proximity effect in annular aperture imaging

Poster-077	Jiaming Gao , Shane Xu , Shuang Li (<i>Technology Development Dept. of Lithography, SiEn Co., Ltd.</i>) Enhancing Overlay Control and Thermal Management Strategies for DUV Reticles with Small Field
Poster-078	Kuizhi Xiao, Tao Zhu, Qin Li, Chenyang Ding (<i>Fudan University</i>) Segmented and Stitchable Fourth-Order Trajectory Planning for Fast Turn-Around Scanning in Lithography Stages
Poster-085	Jingjing Fan, Chong Wang, Haoxin Zuo, Fu Li, Yujin Jia, Shuoyu Xia, Yaokun Li, Qingchen Cao*, Jiangliu Shi (<i>Beijing Superstring Academy of Memory Technology</i>) ILT-Guided SRAF generation for optimizing lithography pattern performance
Poster-088	Yu Feng¹, Liyi Zhou¹, Haoyu Wang¹, Yiming Xu¹, Xinliang Li², and Shisheng Xiong^{1,2} (<i>¹Fudan University, China; ²Zhangjiang Laboratory</i>) Advancing Manufacturability in DSA-Aware Layout Decomposition through Reinforcement Learning
Poster-090	Xiaochen Zhou, Ganlin Song, Xinli Zhou, Jiahao Xi, Jinghong Liu, Mingyi Yao, Miao Jiang*, Jiangliu Shi (<i>Beijing Superstring Academy of Memory Technology</i>) Research on Imaging Quality near the Resolution Limit in Deep Ultraviolet Lithography
Poster-092	Hailong Zhu*, Amigo Li, Steven Luo, Allen Wu, Yong Li, Deming Dong (<i>Nexchip Semiconductor Corporation</i>) Research on the advanced lithography materials by optimizing dark-field defect inspection
Poster-095	Kaining Zhang^{1,2}, Lijun Zhou^{1,2}, Li Chen³, Jinming Gao^{1,2}, Xuan Zhuo^{1,2}, Peng Feng³, Zhongliang Li^{3,*}, Dong Liu^{1,2,*}, Xiangzhao Wang^{1,2,3*} (<i>¹Zhejiang University, 310027; ²ZJU-Hangzhou Global Scientific and Technological Innovation Center; ³Shanghai Institute of Optics and Fine Mechanics, Chinese Academy of Sciences</i>) A Lithography Alignment Measurement System Based on Sinusoidal Phase Modulation of Vortex Beams
Poster-096	Liao Wen Chao, Cui Jia Hao, Han Chun Chieh* (<i>LONGTU MASK TECHNOLOGY CO., LTD</i>) The Thermal Effect Prevention by Multi-Pass Printing
Poster-101	Yufan Lin ¹, Yingxiong Guo ¹, Yanbin Gong ², Shengrui Zhang ², C.M. Hu ², T.H. Ying ¹,Wenzhang Li ^{1,*} (<i>¹Fujian Jinhua Integrated Circuit Co., Ltd; ²Dongfang Jingyuan Electron Co., Ltd.</i>) Etch model application in layer to layer check
Poster-103	Chen Xu ^{1,2}, Jianjun He ¹, Huie Zhu ^{1,2,*} (<i>¹ Shanghai University, Shanghai; ²Zhangjiang Laboratory</i>) Molecular weight and polydispersity effects on electron beam lithography performance of RAFT-mediated PMMA
Poster-104	Tatsi Iao ¹, Fengnien Tsai ¹, T.H.Ying ¹, Shengrui Zhang ², Xinchen You ², Yutong Wang ², Chenjin Wang ², Yanbin Gong ², C.M. Hu², Wenzhang Li^{1,*} (<i>¹ Fujian Jinhua Integrated Circuit Co., Ltd;</i>

	<i>²Dongfang Jingyuan Electron Co., Ltd.)</i> Unified Etch-OPC Modeling for Enhanced Target Fidelity
Poster-105	Hangle Guo¹, Fengnien Tsai¹, T.H.Ying¹, C.M.Hu², Yanbin Gong², Siqu Wang², Shengrui Zhang², Wenzhang Li^{1,*} (<i>¹ Fujian Jinhua Integrated Circuit Co., Ltd; ²Dongfang Jingyuan Electron Co., Ltd.)</i>) Defects detection through etching model
Poster-111	Shengsheng Sun [*], Hailin Wu, Xin Chen, Lin Jia (<i>Lithography Equipment Manufacturing Technology Innovation Center</i>) A Wiener Model-Based Dose Prediction Method for Optical Transient Effects in Lithography
Poster-112	Mia Hu [*], Hao Wu (Jieretech) Development of in-situ wireless temperature measurement for wafers with an accuracy better than 0.5mK
Poster-113	Ziqiang Liang, Di Liang, Yaokun Li, Kaicong Liu, Xin Wei, Jinghong Liu, Jiangliu Shi, Guowei Jiang[*] (<i>Beijing Superstring Academy of Memory Technology</i>) An automated DBO mark generation approach based on python
Poster-114	Dinghai Rui,^{1,2,3} Libin Zhang,^{1,2,3} Yajuan Su,^{1,2,3} Yi Tong,⁴ Yifan Wu,⁴ Shengsheng Sun,⁴ and Yayi Wei,^{1,2,3,*} (<i>¹IMECAS; ² UCAS; ³ State Key Laboratory of Fabrication Technologies for Integrated Circuits; ⁴Lithography Equipment Manufacturing Technology Innovation Center</i>) Transient and steady-state exposure models of mask and their influence on overlay accuracy
Poster-115	Di Liang, Ziqiang Liang, Kaicong Liu, Yaokun Li, Xin Wei, Jinghong Liu, Jiangliu Shi, Guowei Jiang[*] (<i>Beijing Superstring Academy of Memory Technology</i>) Genetic Algorithm-Driven OVL Mark Placement Optimization for Multi-Layer Reticles Based on Maximum nMU Metric
Poster-123	Xiaotong Xu, Fang Yu, Shujing Lyu[*], Yue Lu (<i>East China Normal University</i>) SEM image editing with continuous exposure dose control for lithography process
Poster-128	KunTang ¹, Jie Liang ¹, Liming Sun ², Bangcheng Yan ², Min Zhong ^{2,*} (<i>¹School of Microelectronics, Shanghai University, China; ²Shanghai Integrated Circuit Research and Development Center Co., Ltd.)</i>) Design and comparison of tri-layer and quad-layer photoresist schemes for patterning phase-change memory cells under immersion ArF lithography
Poster-129	Yahui Jing, Zhen Wu, Haonan Wang[*] (<i>Lithography Equipment Manufacturing Technology Innovation Center</i>) An Evaluation Method for Image Plane Stability in Projection Exposure Systems
Poster-130	Ming Hao ¹, Pan Zeng ², Bingqian Ma ², Ran Ji ^{2,*}, Wanjiao Zhang ^{1,*} (<i>¹University of Chinese Academy of Sciences, Beijing, China, 100049; ²Qingdao Germanlitho Co., Ltd)</i>)

	Hierarchical digital resist deposition for localized thickness engineering in Nanoimprint Lithography
Poster-131	Yingshuai Liu, Tengfei Yan* (<i>Shanghai University</i>) Quantitative Determination of the Acid Quantum Yield of Nonionic Photoacid Generators Using ¹ H Nuclear Magnetic Resonance Spectroscopy
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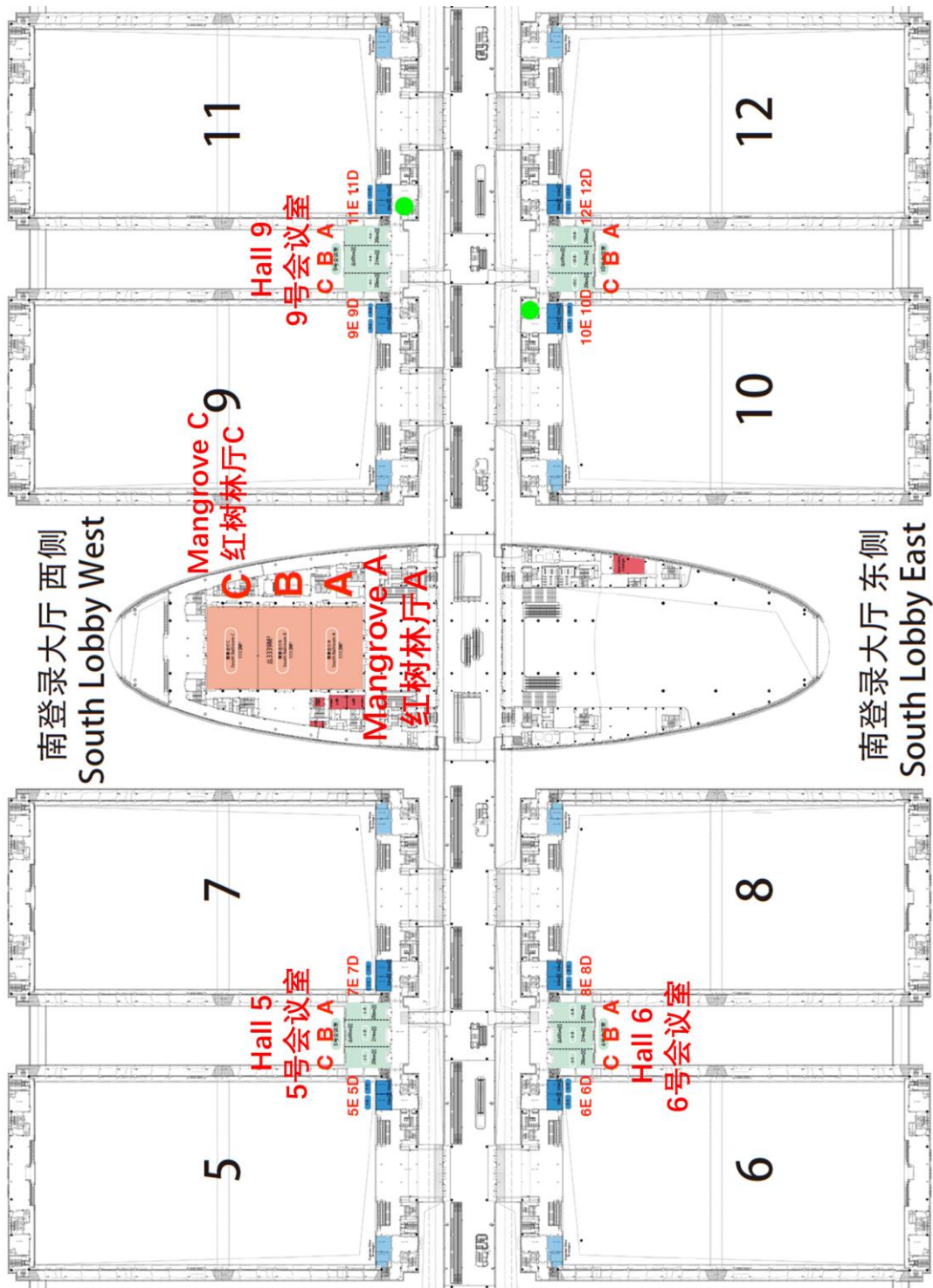
Agenda is subject to change

For update agenda and further information, please visit the website: www.iwaps.org

Events

Item	Date	Time	Location
Registration	09 Sep.	14:00-17:00	Front of Mangrove A, Second Floor, South Lobby, Shenzhen World
	10-11 Sep.	08:00-17:00	深圳国际会展中心南登录大厅，2 层，红树林厅 A 前
Main Meeting	10 Sep.	08:30-18:00	Mangrove A, Second Floor, South Lobby, Shenzhen World 深圳国际会展中心南登录大厅，2 层，红树林厅 A
Parallel Meeting	11 Sep.	08:30-17:30	Hall 5/6/9, 2nd Floor, South Lobby, Shenzhen World 深圳国际会展中心南登录大厅，2 层 5 号 /6 号/9 号会议室
Poster Session	10 Sep.	11:50-13:50	Outdoor of Mangrove A 红树林厅 A 前廊
Group Photo	10 Sep.	10:10-10:40	South Lobby West (1 st Floor) 南登录大厅西侧门口（一层）
Banquet	10 Sep.	18:30-20:30	Mangrove C 红树林厅 C
Coffee Break	10-11 Sep.	10:10-10:50 14:50-16:00	Outdoor of Mangrove A 红树林厅 A 前廊
Lunch	10-11 Sep.	12:00-13:00	Mangrove C 红树林厅 C

南登录大厅二层主会场、分会场平面图



Locations

深圳国际会展中心 Shenzhen World

